**Amendments to the Claims**:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A two-component adhesive **K**, consisting of:

a component **K1** and a component **K2**, wherein:

~~(a)~~(a) component **K1** comprises:

at least one epoxy resin **A** having more than one epoxy group per molecule on average;

at least one epoxy adduct **B**, wherein each epoxy adduct B has more than one epoxy group and more than one hydroxyl group per molecule on average;

at least one product **F** of a reaction between an epoxy adduct **B** and a compound **C** with at least two isocyanate groups; and

at least one curing agent **D** for epoxy resins, which is activated by elevated temperature;

and

**(b)** component **K2** comprises:

at least one compound **E** with at least two isocyanate groups;

wherein:

epoxy adduct **B** is an epoxy adduct **B1** obtained from at least one dicarboxylic acid and at least one diglycidyl ether, and is optionally combined with an epoxy adduct **B2**, obtained from at least one bis(aminophenyl)sulfone isomer or at least one aromatic alcohol and at least one diglycidyl ~~ether.~~ether,

compound **C** is a polyurethane prepolymer **C2** having isocyanate groups, which is synthesized from at least one polyisocyanate **C1** and from at least one

polyol, the isocyanate groups of **C1** are in stoichiometric excess relative to the hydroxyl groups of the polyol such that the resulting polyurethane prepolymer **C2**, after reaction of all the hydroxyl groups of the polyol, has a free isocyanate group content from 0.5 to 5 wt.% relative to the total polyurethane prepolymer **C2**, and

the ratio of **K1** and **K2** is such that the OH/NCO ratio is > 2:1.

2. (Previously Presented) The adhesive according to claim 1, wherein epoxy resin **A** is a liquid resin.

3. (Previously Presented) The adhesive according to claim 1, wherein the dicarboxylic acid is a dimeric fatty acid and the diglycidyl ether is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, and bisphenol A/F diglycidyl ether.

4. (Previously Presented) The adhesive according to claim 1, wherein:

epoxy adduct **B2** is prepared from at least one aromatic alcohol and at least one diglycidyl ether,

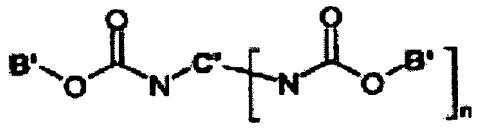
the aromatic alcohol is selected from the group consisting of 2,2-bis(4-hydroxyphenyl)propane, bis(4-hydroxyphenyl)methane, bis(4-hydroxyphenyl)sulfone, hydroquinone, resorcinol, pyrocatechol, naphthohydroquinone, naphthoresorcinol, dihydroxynaphthalene, dihydroxyanthraquinone, dihydroxybiphenyl, 3,3-bis(*p*-hydroxyphenyl)phthalide, 5,5-bis(4-hydroxyphenyl)hexahydro-4,7-methanoindane, and isomers thereof ; and

the diglycidyl ether is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, and bisphenol A/F diglycidyl ether.

5. (Previously Presented) The adhesive according to claim 1, wherein epoxy adduct **B** has a molecular weight of 700-6000 g/mol.

6. (Canceled)

7. (Previously Presented) The adhesive according to claim 1, wherein the reaction product **F** has the structure



wherein **B′** is structurally identical to epoxy adduct **B**, except one hydroxyl groups is missing, and wherein **C′** is structurally identical to compound **C**, except all the isocyanate groups are missing, and wherein n+1 represents the number of isocyanate groups in compound **C**.

8. (Previously Presented) The adhesive according to claim 1, wherein curing agent **D** is a latent curing agent selected from the group consisting of dicyanodiamide, guanamine, guanidine, and aminoguanidine.

9. (Previously Presented) The adhesive according to claim 1, wherein compound **E** is a polyisocyanate or a polyurethane prepolymer having isocyanate groups, which is synthesized from at least one polyisocyanate and from at least one polyol.

10. (Previously Presented) The adhesive according to claim 1, wherein a total proportion of epoxy resin **A** and epoxy adduct **B** together is 10-60 wt.% based on a total weight of adhesive **K**.

11. (Previously Presented) The adhesive according to claim 1, further comprising at least one filler in a proportion of 5-30 wt.% based on a total weight of adhesive **K**.

12. (Previously Presented) The adhesive according to claim 1, further comprising at least one reactive diluent with epoxy groups.

13. (Previously Presented) A method for fabrication of a semifinished product **H** using the adhesive according to claim 1, comprising:

heating component **K1** to a temperature between 130°C and 60°C;

mixing together components **K1** and **K2**;

applying the mixed adhesive **K** to a flat substrate **S1**; and

contacting the adhesive **K** on substrate **S1** with a flat substrate **S2** so that the mixed adhesive **K** is placed between substrates **S1** and **S2**.

14. (Previously Presented) The method according to claim 13, wherein the flat substrate **S1** consists of the same material as the flat substrate **S2**.

15. (Previously Presented) The method according to claim 13, wherein at least one of substrates **S1** or **S2** is sheet metal.

16. (Previously Presented) The method according to claim 15, wherein the sheet metal has a thickness between 0.5 mm and 0.1 mm.

17. (Canceled)

18. (Previously Presented) The method according to claim 13, wherein the semifinished product **H** is subsequently coiled into a roll and stored in the form of a coil; or

is cut to length and the semifinished product **H**, cut to length, is stored in the form of a stack.

19. (Previously Presented) The semifinished product **H** fabricated according to the method of claim 13.

20. (Previously Presented) A method for fabrication of a sandwich composite **S**, wherein the semifinished product **H** according to Claim 19 undergoes a forming process and is heated to a temperature between 130°C and 230°C.

21. (Previously Presented) The sandwich composite **S** fabricated according to claim 20.

22. (Previously Presented) An automotive assembly composite, comprising the sandwich composite **S** according to claim 21.

23. (Previously Presented) The adhesive according to claim 1, wherein epoxy resin **A** is a liquid resin selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, and bisphenol A/F diglycidyl ether.

24. (Previously Presented) The adhesive according to claim 3, wherein the dicarboxylic acid is a dimeric C4-C20 fatty acid.

25. (Previously Presented) The adhesive according to claim 1, wherein epoxy adduct **B** has a molecular weight of 900-4000 g/mol.

26. (Previously Presented) The adhesive according to claim 1, wherein epoxy adduct **B** has a molecular weight of 1000-3300 g/mol.

27. (Previously Presented) The adhesive according to claim 6, wherein the polyol is a polyoxyalkylene polyol.

28. (Previously Presented) The adhesive according to claim 6, wherein the polyol is a polyoxyalkylene diol.

29. (Previously Presented) The adhesive according to claim 9, wherein the polyol of compound **E** is a polyoxyalkylene polyol.

30. (Previously Presented) The adhesive according to claim 9, wherein the polyol of compound **E** is a polyoxyalkylene diol.

31. (Previously Presented) The adhesive according to claim 1, wherein a total proportion of epoxy resin **A** and epoxy adduct **B** together is 15-55 wt.% based on a total weight of adhesive **K**.

32. (Previously Presented) The adhesive according to claim 1, further comprising at least one filler in a proportion of 10-25 wt.% based on a total weight of adhesive **K**.

33. (Previously Presented) The method according to claim 13, wherein:

the step of contacting the adhesive **K** on substrate **S1** with a flat substrate **S2** further comprises applying pressure to at least one of substrates **S1** or **S2** during or after contact is made with substrate **S2**.

34. (Previously Presented) The method according to claim 15, wherein the sheet metal is steel sheet or aluminum sheet.

35. (Previously Presented) The method according to claim 34, wherein the sheet metal is oiled.

36. (Previously Presented) The method according to claim 15, wherein the sheet metal has a thickness between 0.4 mm and 0.2 mm.

37. (Previously Presented) The method according to claim 13, wherein components **K1** and **K2** are mixed in such a ratio that the OH/NCO ratio is 2:1 to 50:1.

38. (Previously Presented) A method for fabrication of a sandwich composite **S**, wherein the semifinished product **H** according to Claim 19 undergoes a forming process and is heated to a temperature between 170°C and 190°C.

39. (Previously Presented) The method according to claim 13, wherein component **K1** is heated to a temperature between 130°C and 80°C.

40. (Previously Presented) The method according to claim 13, wherein component **K1** is heated to a temperature between 100°C and 90°C.